



produced upon requests.

Model: Aluminum Nitride Ceramic Substrate

Polished Aluminum Nitride (ALN) Ceramic Substrate

GREENWAY is a manufacturer and supplier of Polished Aluminum Nitride (ALN) Ceramic Substrate. The aluminum nitride (AIN) ceramic has high thermal conductivity (5-10 times as the alumina ceramic), low dielectric constant and dissipation factor, good insulation and excellent mechanical properties, non-toxic, high thermal resistance, chemical resistance , and the linear expansion coefficient is similar with Si, which is widely used in communication components, high power led, power electronic devices and other fields. Special spec products can be

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Aluminum Nitride (ALN) Ceramic Substrate PERFORMANCE

- High thermal conductivity, high flexural strength, high temperature
- Good electrical insulation
- Low dielectric constant and loss
- Able to be laser drilled, metallized, plated and brazed





Regular Dimensions of AIN Substrate/Wafer

Specifications/ Thickness	0.254	0.381	0.5	0. 635	0.8	1.0	1.5	2.0	2.5	3.0
114.3*114.3mm	*	*	*	*	*	*	*	*	*	*
120*120mm	*	*	*	*	*	*	*	*	*	*
124*124mm		*	*	*	*	*	*	*	*	*
152*152mm				*	*	*	*	*	*	*
140*190mm				*	*	*	*	*	*	*
152*203mm					*	*	*	*	*	*
203*203mm					*	*	*	*	*	*
220*220mm						*	*	*	*	*
110*290mm					*	*	*	*	*	*

PS: Other dimensions which are not listed are available upon your requests.

Aluminum Nitride (ALN) Ceramic Substrate Features

- 1.Uniform microstructure
- 2.High thermal conductivity* (70-180 Wm-1K-1), tailored via processing conditions and additives
- 3. High electrical resistivity
- 4. Thermal expansion coefficient close to that of Silicon
- 5.Resistance to corrosion and erosion
- 6.Excellent thermal shock resistance
- 7. Chemically stable up to 980°C in H2 and CO2 atmospheres, and in air up to 1380°C (surface oxidationoccurs around 780°C; the surface layer protects the bulk up to 1380°C).



